

ABSTRACT OF THE DISCLOSURE

A semiconductor device includes a semiconductor substrate having a plurality of connecting pads on one surface, an insulating film formed on one surface of the semiconductor substrate. The insulating film has holes each corresponding to one of the connecting pads, and a recess having a bottom surface depressed from the upper surface in the direction of thickness. Interconnections are formed on an upper surface of the insulating film or on the bottom surface of the recess, and connected to the connecting pads through the holes in the insulating film.